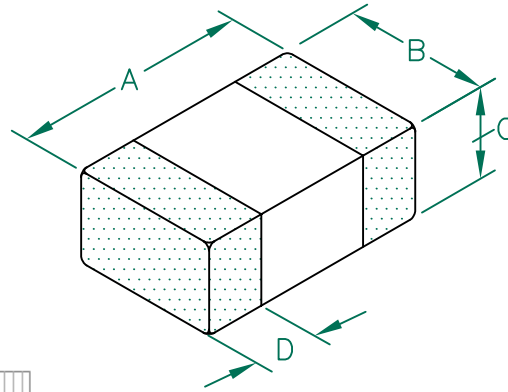


CPI1008K1R2R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.50 [.098]	+ 0.20 [.008]
B	2.00 [.079]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.10 [.004]
D	0.60 [.024]	+ 0.20 [.008]

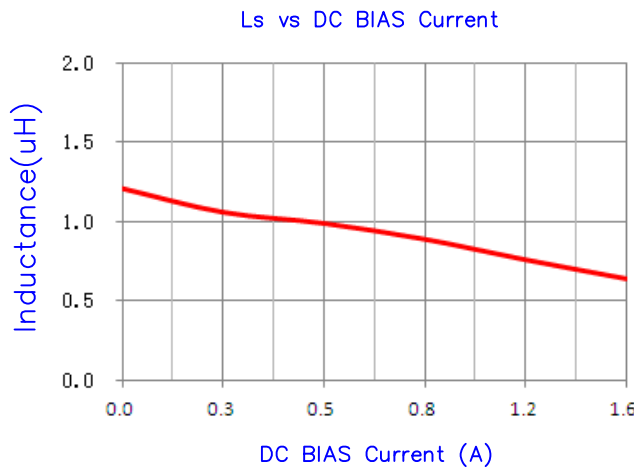
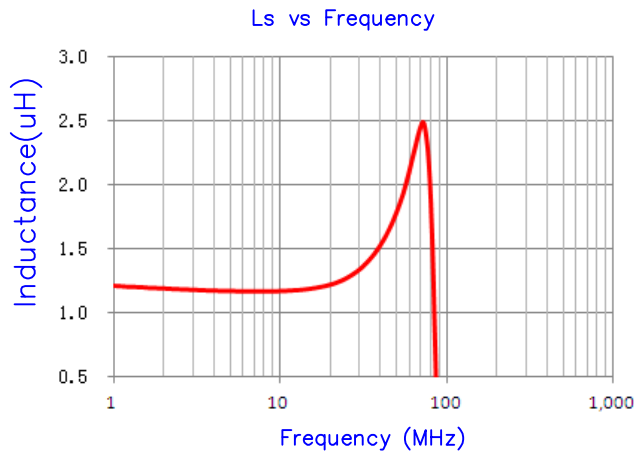


ELECTRICAL CHARACTERISTICS:

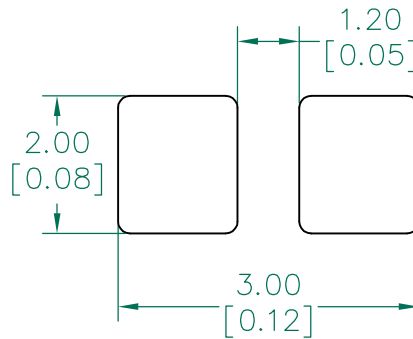
	L (μ H) @ 1MHz $\pm 20\%$	DCR (Ω) $\pm 25\%$	I (Max)
Nom	1.20	0.1100	
Min	0.96	0.0825	
Max	1.44	0.1375	1600mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

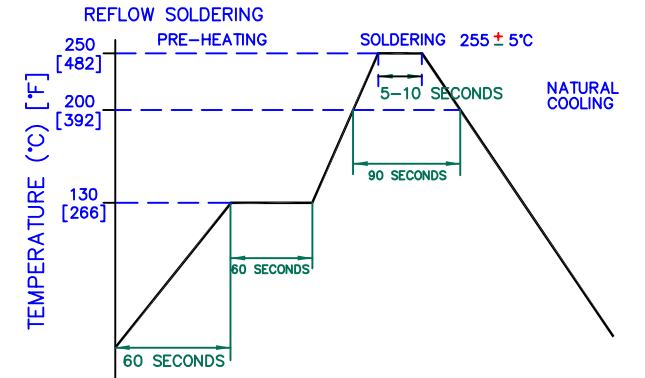


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
PROJECT/PART NUMBER:				REV			
C				C			
UPDATE PAD DIMENSION ROHS				PART TYPE:			
07/08/14				CO-FIRE			
QU				DRAWN BY:			
CPI1008K1R2R-10				QU			
B				DATE:			
UPDATE LAIRD LOGO AND NOTES 5				03/01/11			
08/05/13				SCALE:			
QU				NTS			
A				SHEET:			
ORIGINAL DRAFT				03/01/11			
QU				CAD #			
REV				TOOL #			
DESCRIPTION				DATE			
INT				CP11008K1R2R-10-C			
				1 of 1			

